

Product Summary

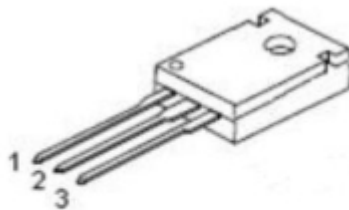
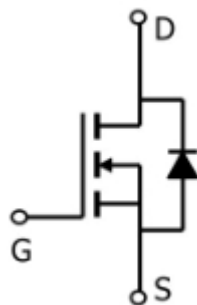
$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
800V	$0.65\Omega@10V$	12A

Feature

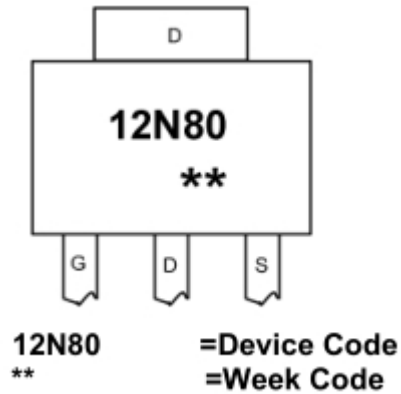
- Fast Switching
- Low Gate Charge and $R_{DS(on)}$
- 100% Single Pulse avalanche energy Test

Applications

- DC-DC Converter
- Ideal for high-frequency switching and synchronous rectification

Package**TO-247(1:G 2:D 3:S)****Circuit diagram**

Marking



Absolute maximum ratings

(T_a=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	800	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous(T _C = 25°C)	I _D	12	W
Pulsed Drain Current ²	I _{DM}	48	A
Single Pulse Avalanche Energy ³	E _{AS}	891	mJ
Total Power Dissipation (T _C = 25°C)	P _D	300	W
Thermal Resistance Junction- Case ¹	R _{θJC}	0.42	°C/ W
Storage Temperature Range	T _{STG}	-55~ +150	°C
Operating Junction Temperature Range	T _J	-55~ +150	°C

Electrical characteristics

(T_A=25°C, unless otherwise noted)

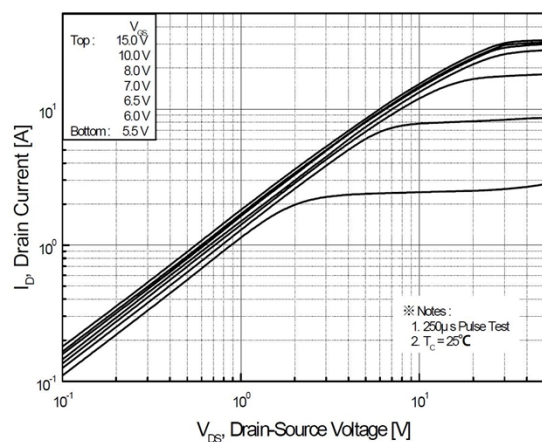
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} = 0V, I _D =250μA	800			V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =720V,V _{GS} = 0V , T _J =25°C			10	uA
Gate-body leakage current	I _{GSS}	V _{GS} =±20V , V _{DS} =0V			±100	uA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	3	4	5	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =6A		0.65	0.81	Ω
Dynamic characteristics ⁴						
Input Capacitance	C _{iSS}	V _{DS} =25V,V _{GS} =0V, f=1MHz		2732		pF
Output Capacitance	C _{oSS}			278		
Reverse Transfer Capacitance	C _{rSS}			28		
Switching Characteristics						
Total Gate Charge(4.5V)	Q _g	V _{DS} =640V, V _{GS} =10V, I _D =12A		67		nC
Gate-Source Charge	Q _{gS}			16		
Gate-Drain Charge	Q _{gd}			31		
Turn-On Delay Time	T _{d(on)}	V _{DD} =400V, V _{GS} =10V, R _G =25Ω, I _D =12A		61		nS
Rise Time	T _r			149		
Turn-Off Delay Time	T _{d(off)}			160		
Fall Time	T _f			113		

Note :

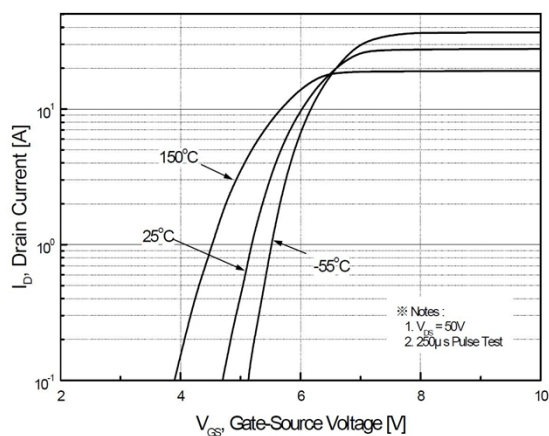
1. The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
3. The EAS data shows Max. rating . The test condition is R_G =25Ω ,L=13mH

Typical Characteristics

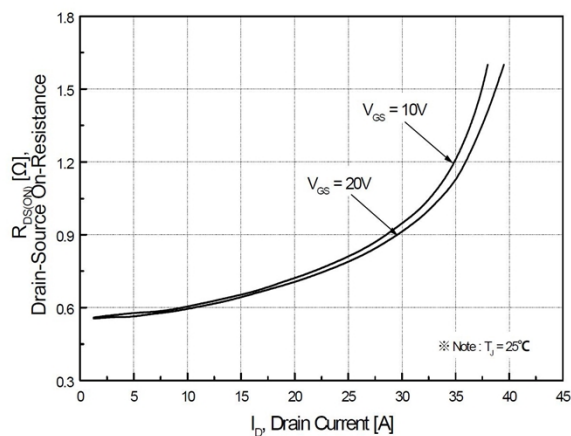
On-Region Characteristics



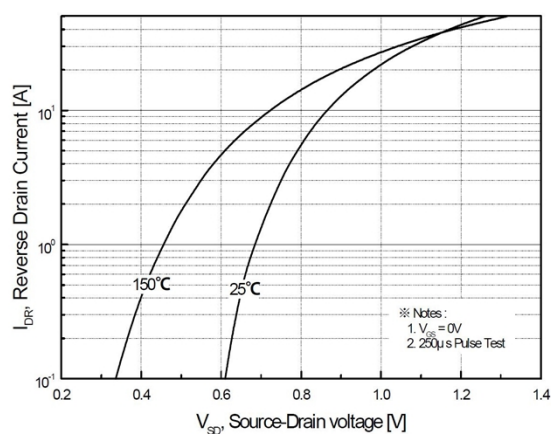
Transfer Characteristics



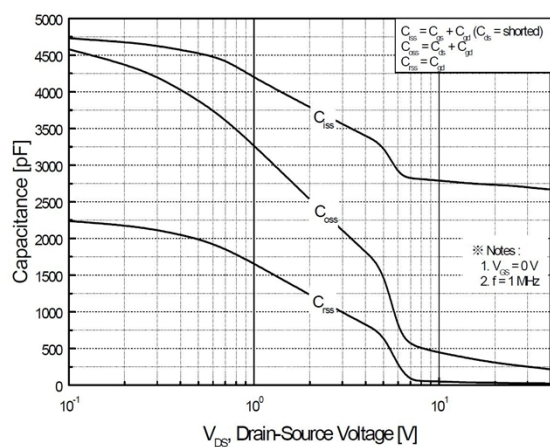
On-Resistance Variation vs. Drain Current and Gate Voltage



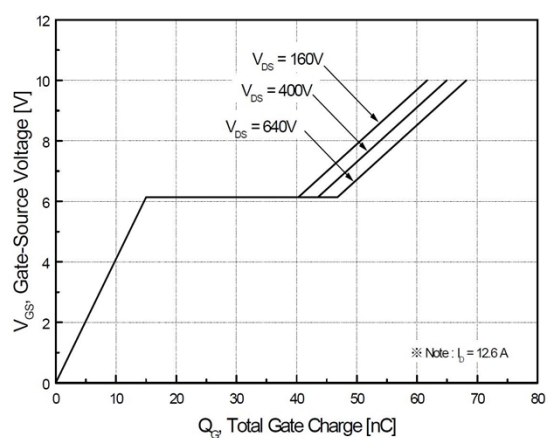
Body Diode Forward Voltage Variation vs. Source Current and Temperature



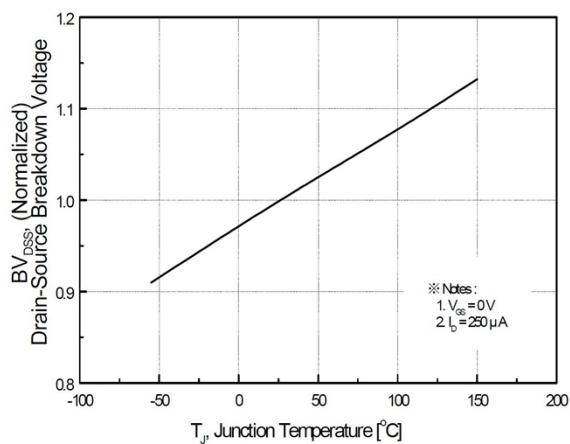
Capacitance Characteristics



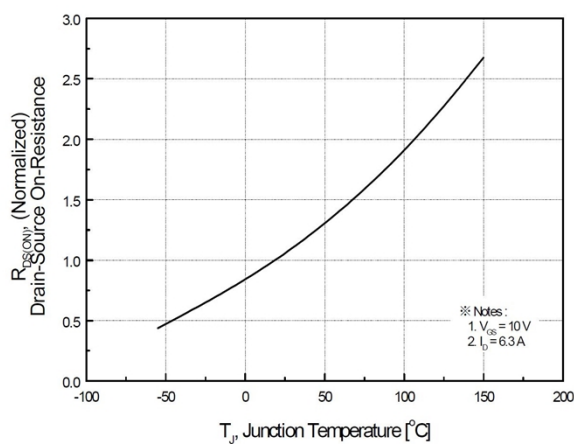
Gate Charge Characteristics



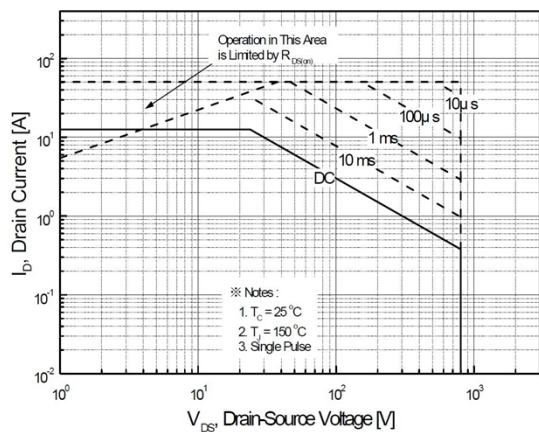
**Breakdown Voltage Variation
vs. Temperature**



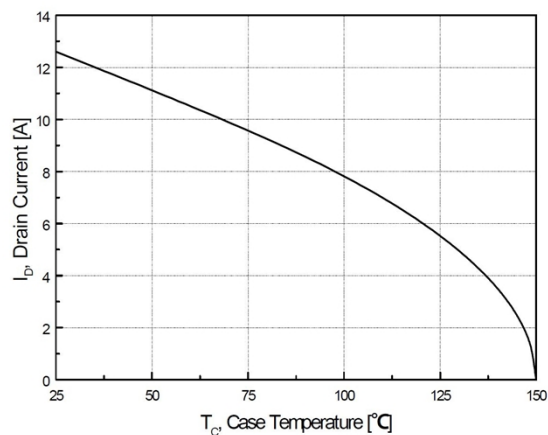
**On-Resistance Variation
vs. Temperature**



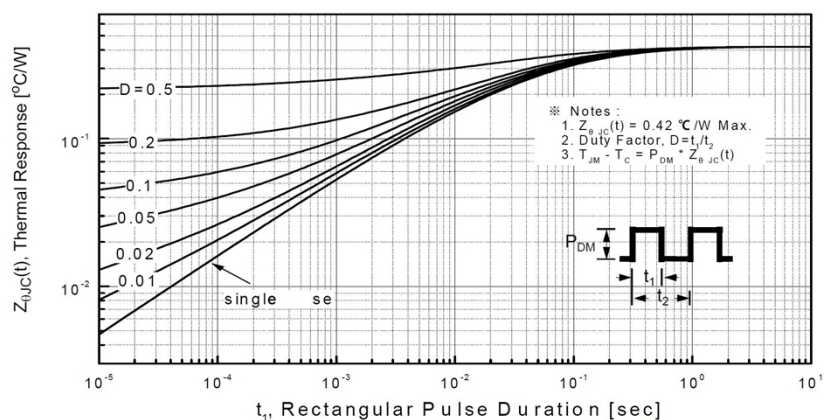
Maximum Safe Operating Area



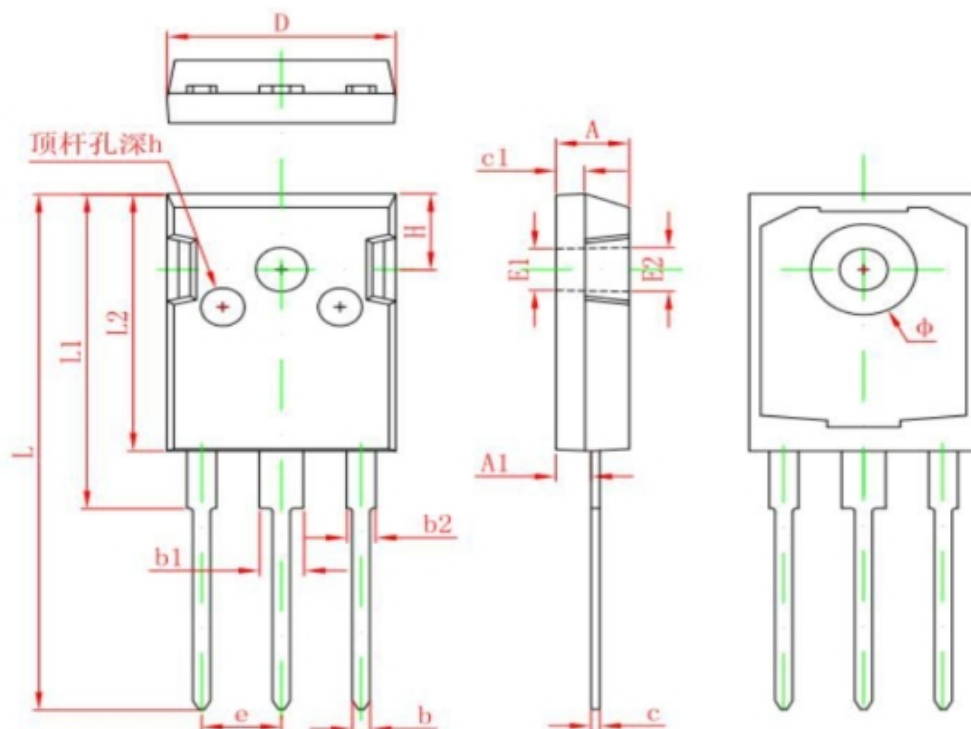
**Maximum Drain Current
vs. Case Temperature**



Transient Thermal Response Curve



TO-247 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.850	5.150	0.191	0.200
A1	2.200	2.600	0.087	0.102
b	1.000	1.400	0.039	0.055
b1	2.800	3.200	0.110	0.126
b2	1.800	2.200	0.071	0.087
c	0.500	0.700	0.020	0.028
c1	1.900	2.100	0.075	0.083
D	15.450	15.750	0.608	0.620
E1	3.500 REF.		0.138 REF.	
E2	3.600 REF.		0.142 REF.	
L	40.900	41.300	1.610	1.626
L1	24.800	25.100	0.976	0.988
L2	20.300	20.600	0.799	0.811
Φ	7.100	7.300	0.280	0.287
e	5.450 TYP.		0.215 TYP.	
H	5.980 REF.		0.235 REF.	
h	0.000	0.300	0.000	0.012